



/ Revised record

D	2017-5				
E	2021-1-27	4/7	0.5-0.8	e0.5-0.7 5 7	

/ Descriptions

2.0A

MBF

2.0A Surface Mount Schottky Bridge,MBF thin package.

/ Features

40V~200V

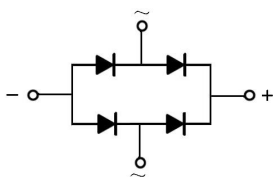
2.0A

High Surge Current Capability,Reverse Voltage:40to200V,Forward Current:2.0A,Designed for Surface Mount Application.Halogen free product.

/ Applications

General purpose.

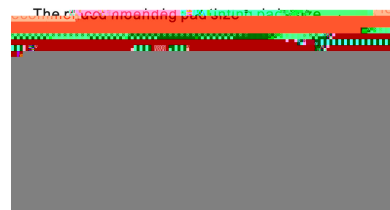
/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating					Unit
		MB24F	MB26F	MB28F	MB210F	MB220F	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	40	60	80	100	200	V
Maximum RMS Voltage	V _{RMS}	28	42	56	70	140	V
Maximum DC Blocking Voltage	V _{DC}	40	60	80	100	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	2.0					A
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	50		40			A
Typical Junction Capacitance ¹⁾	C _j	220	80				pF
Typical Thermal Resistance ²⁾	R _{θJA}	75					°C/W
Operating Junction Temperature Range	T _j	-55~+125					°C
Storage Temperature Range	T _{stg}	-55~+150					°C

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with $4 \times (5 \times 5mm^2)$ copper pad.

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	数值 Rating					Unit
			MB24F	MB26F	MB28F	MB210F	MB220F	
Max Instantaneous Forward Voltage	V_F	$I_F=2.0A$	0.55	0.70	0.85			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_a=25^\circ C$	0.5			0.3		mA
		$T_a=100^\circ C$	10			5.0		mA

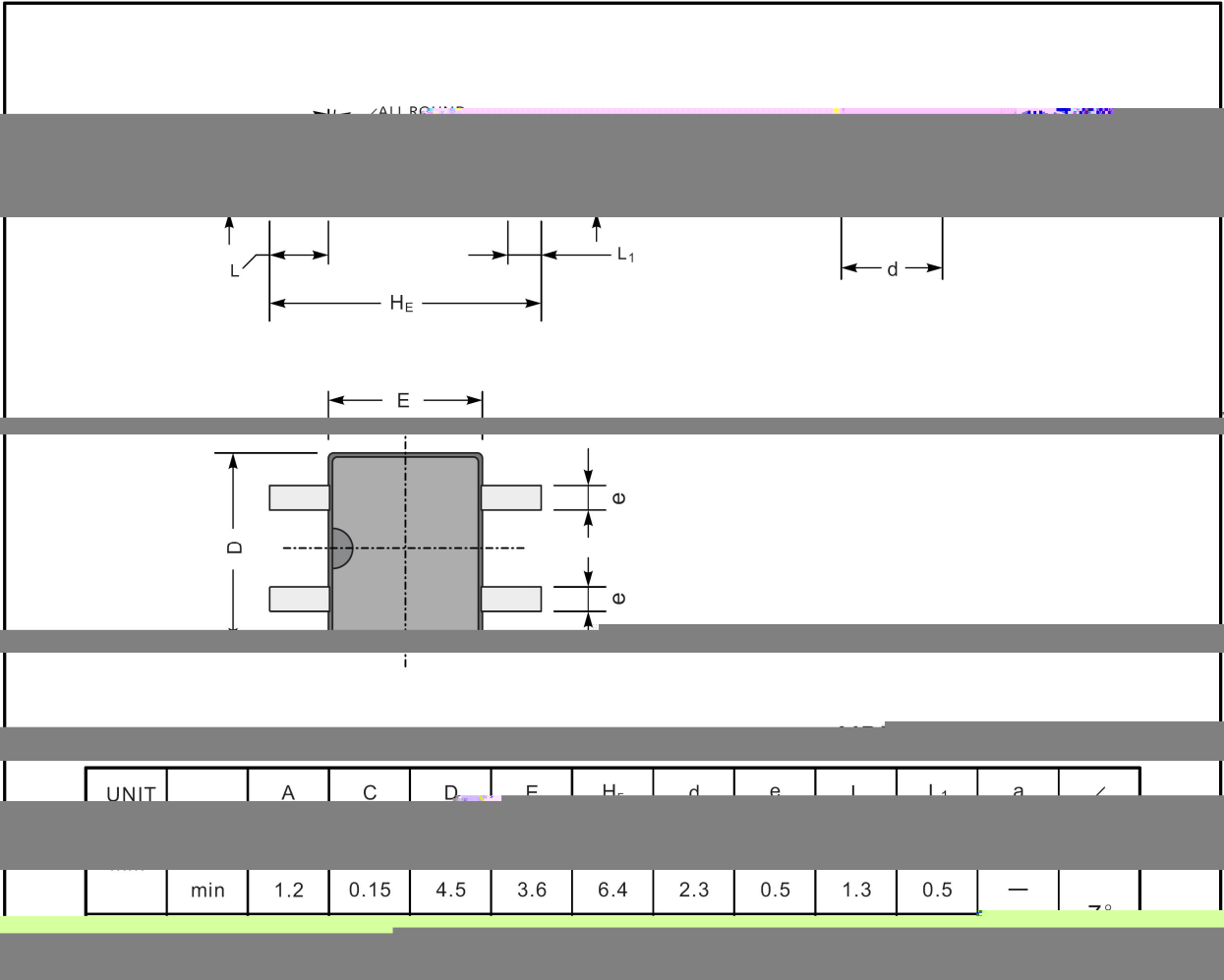


/ Electrical Characteristic Curve



/ Package Dimensions

MBF

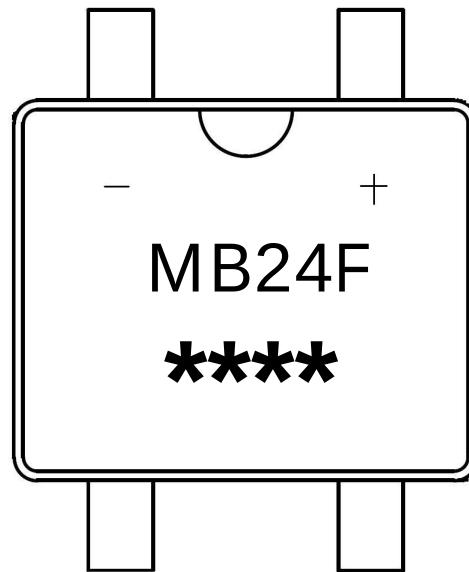


MB24F~MB220F

Rev.E Jan.-2021

DATA SHEET

/ Marking Instructions



MB24F

1 *

3 *

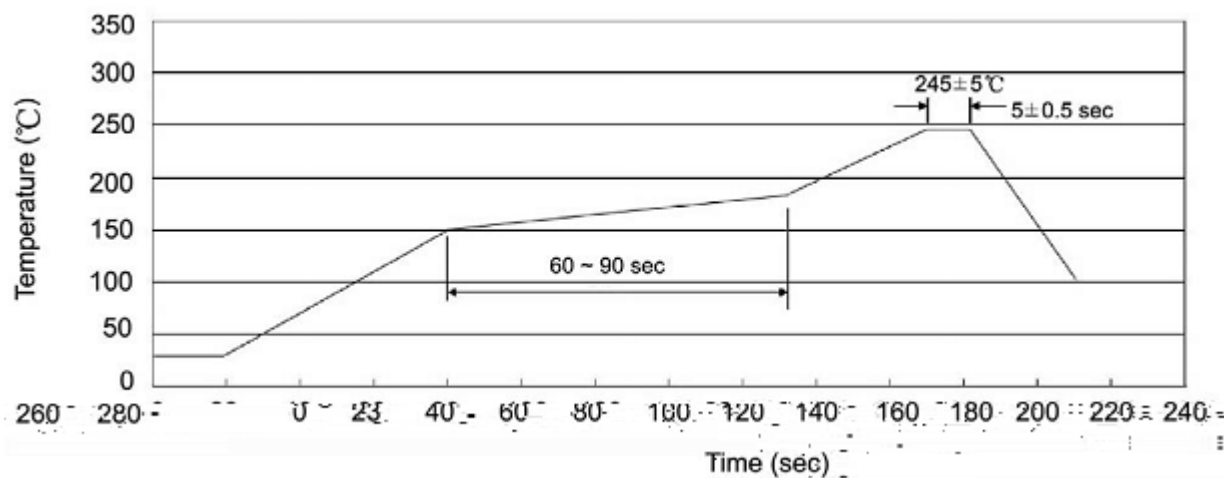
Note:

MB24F Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|--|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150°C, Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5°C, Duration:5±0.5sec. |
| 3 | | 2 | 10°C/sec. | | 3. Cooling Speed: 2~10°C/sec. |

/ Resistance to Soldering Heat Test Conditions

3 260±5°C 1hhU 10±1 sec. Temp.:260±5°C Time:10±1 sec

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱 /